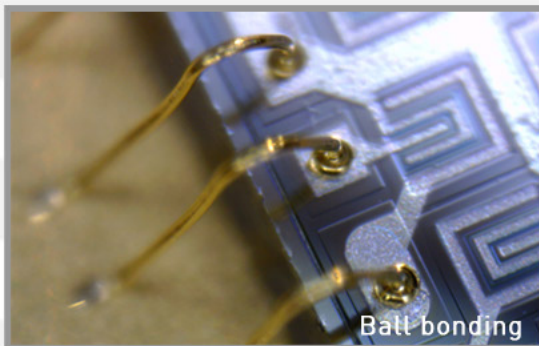


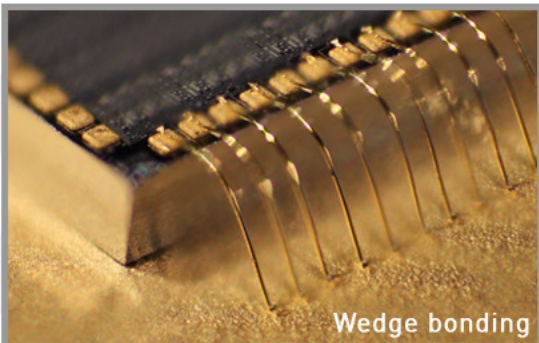


HB05 Wedge & Ball Bonder

Manual Wire Bonder



Ball bonding



Wedge bonding

- + Wedge, Ball, Bump and Ribbon bonding
- + 17 μ to 75 μ Wire and 25 μ x 250 μ Ribbon
- + 4,3" TFT Display & Multi Button
- + Deep-Access Bond Head 16mm
- + Bond Arm Length 165mm
- + Motorized Tail Control
- + 20 Program Storage Capacities
- + Electronic Ball Size Control

HB05 Thermosonic Wire Bonder for Wedge & Ball Bonding

The HB05 is a **Bench Top Size Wire Bonder**, ideal for laboratories and pilot production lines.
One Bond Head for bonding in Ball/Wedge or Wedge/Wedge bonding mode. Only tool change necessary.
Easy operation with **TFT Display**, direct access and simple adjustment of all bond parameters.

Technical Specifications

Bonding Methode Wedge-Wedge, Ball-Wedge, Ribbon- & Bumb- bonding

Gold wire diameter 17 - 75 μ (0,7 - 3 mil)

Aluminium wire diameter 17 - 75 μ (0,7 - 3 mil)

Ribbon size max. 25 x 250 μ (1x 8 mil)

Ultrasonic system 62 kHz Transducer PLL Control

Ultrasonic power 0 - 5 Watt Output

Bond time 0 - 1 sec.

Bond force 5 - 130 cNm

Bonding tool 1,58 \emptyset 19 mm length (0,0624" x 0,750")

Motorised Wire Spool 50,8 mm (2")

Wire termination Bond Head Tear

Wire feed angle 90°

Clamp movement Motorized, Up / Down

Ball size control Electronic

Throat depth 165 mm (6,7")

Fine Table motion 10 mm (0,4 ")

Mouse ratio 6:1

Temperature controller up to 250°C +/- 1°C

Electrical Requirements 100 - 240V +/- 10% 50/60 Hz 10A max.

Physical Dimensions 550 x 450 x 250mm

Weight Net 25 kg

Industry Standards CE standards

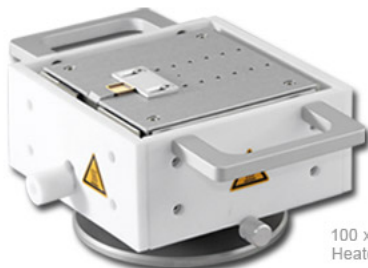
Accessories:



60mm \emptyset
Heater Stage



90mm \emptyset
Heater Stage



100 x 100mm
Heater Stage



Bondstart Kit



Franz & Fabian Hickmann GbR

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Specifications are subject to change without prior notice